ABSTRACT

DEVICE SEPARATION STRUCTURE AND SEMICONDUCTOR DEVICE IMPROVED IN WIRING STRUCTURE

A semiconductor device has a device region, and a device separation region formed on a semiconductor substrate doped with impurities. And, the device separation region has a metal wiring formed on the surface of the device region or the back surface of the substrate. An aluminum region extending in the longitudinal direction connected to the metal wiring is formed within the device separation region.

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